

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1114in#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 0.987081**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003675	1000000	3723.09936523		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000153	1000000	155.002502441		
Lead Frame	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.169128	580000	171341.59375		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.122472	420000	124074.953125		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.291600</b>	<b>1000000</b>	<b>295416.53125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.021727	1000000	22011.1289062		
		<b>External Plating Total:</b>				<b>0.021727</b>	<b>1000000</b>	<b>22011.1289062</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.002333	1000000	2363.53515625		
<b>Internal Plating Total:</b>				<b>0.002333</b>	<b>1000000</b>	<b>2363.53515625</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001041	750000	1054.62487793		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000347	250000	351.541625977		
<b>Die Attach Total:</b>				<b>0.001388</b>	<b>1000000</b>	<b>1406.16650391</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.089870	135000	91046.2421875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.572506	860000	579999.125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.003329	5000	3372.57080078		
		<b>Encapsulation Total:</b>				<b>0.665705</b>	<b>1000000</b>	<b>674418</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000500	1000000	506.544128418		
					<b>TOTAL MASS (g) :</b>	<b>0.987081</b>		